

# RENESAS TECHNICAL UPDATE

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Product Category	MPU/MCU		Document No.	TN-SY*-A0058A/E	Rev.	1.00
Title	S5D3 Group, S5D5 Group, S5D9 Group, adding LGA/BGA packages with operating temperature -40 to +105 °C support		Information Category	Technical Notification		
Applicable Product	S5D3 Group	Lot No.	Reference Document	S5D3 Microcontroller Group User's Manual Rev.1.10 S5D5 Microcontroller Group User's Manual Rev.1.30 S5D9 Microcontroller Group User's Manual Rev.1.30		
	S5D5 Group S5D9 Group	All				

Additional LGA and BGA packages with operating temperature of Ta = -40 to +105 °C option had been added to the S5D3, S5D5, S5D9 product groups. To incorporate this enhancement into the documentation the part names as shown in Tables 1 to 3 have been added.

Table 1. S5D3 group operating temperature -40 to +105 °C products

Product name	Orderable part number	Package code	Code flash	SRAM	Data flash
R7FS5D37A3A01CLJ	R7FS5D37A3A01CLJ#AC0	PTLG0100JA-A	512kB	256kB	8kB

Table 2. S5D5 group operating temperature -40 to +105 °C products

Product name	Orderable part number	Package code	Code flash	SRAM	Data flash
R7FS5D57C3A01CLK	R7FS5D57C3A01CLK#AC1	PTLG0145KA-A	1MB	384kB	32kB
R7FS5D57A3A01CLK	R7FS5D57A3A01CLK#AC1		512kB		

Table 3. S5D9 group operating temperature -40 to +105 °C products

Product name	Orderable part number	Package code	Code flash	SRAM	Data flash
R7FS5D97E3A01CLK	R7FS5D97E3A01CLK#AC0	PTLG0145KA-A	2MB	640kB	64kB
R7FS5D97C3A01CLK	R7FS5D97C3A01CLK#AC0		1MB		
R7FS5D97E3A01CBG	R7FS5D97E3A01CBG#AC0	PLBG0176GE-A	2MB		
R7FS5D97C3A01CBG	R7FS5D97C3A01CBG#AC0		1MB		

Note: SSP 1.8.0 and SSP configurator will support above -40 to 105°C Product name in May 2021.